

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Kimikazu KANETO	11/13/2009
Minoru HIRATA	11/13/2009
Mitsuyuki MATSUSHITA	11/13/2009
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SINTOKOGIO, LTD.
<b>Street Address:</b>	28-12, Meieki 3-chome, Nakamura-ku Nagoya-shi,
<b>City:</b>	Aichi
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	450-0002
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12602375
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<b>ATTORNEY DOCKET NUMBER:</b>	04632.0140
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<b>Total Attachments: 2</b> source=Assignment04632-0140#page1.tif source=Assignment04632-0140#page2.tif	

OP \$40.00 12602375

JOINT INVENTION  
(U.S. Rights Only)

**ASSIGNMENT**

WHEREAS, We, the below named inventors, (hereinafter referred to as assignors, have made an invention entitled:

Equipment for Molding Mold with Molding Flask and  
Method for Molding Mold with Molding Flask

for which we executed an application for United States Letters Patent concurrently herewith or on \_\_\_\_\_ or filed an application for United States Letters Patent on \_\_\_\_\_ (Application No. \_\_\_\_\_); and

WHEREAS, SINTOKOGIO, LTD., a corporation of Japan, whose post office address is \_\_\_\_\_

28-12, Meieki 3-chome, Nakamura-ku Nagoya-shi Aichi 450-0002 Japan (hereinafter referred to as assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, we, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and we hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY further covenant and agree that we will, without further consideration, communicate with assignee, its successors and assigns, any facts known to us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, WE HEREBY authorize and request the attorneys we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, we have hereunto set our hands.

**First Assignor**

Name: Kimikazu KANETO  
Address: c/o Sintokogio, Ltd., Toyokawa-Seisakusho  
1, Honohara 3-chome, Toyokawa-shi Aichi 442-0061 Japan

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Citizenship: Japan

Signature: 金藤 公一

Date: November 13, 2009

**Second Assignor**

Name: Minoru HIRATA  
Address: c/o Sintokogio, Ltd., Toyokawa-Seisakusho  
1, Honohara 3-chome, Toyokawa-shi Aichi 442-0061 Japan

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Citizenship: Japan

Signature: Minoru Hirata

Date: November 13, 2009

**Third Assignor**

Name: Mitsuyuki MATSUSHITA  
Address: c/o Sintokogio, Ltd., Toyokawa-Seisakusho  
1, Honohara 3-chome, Toyokawa-shi Aichi 442-0061 Japan

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Citizenship: Japan

Signature: M. MATSUSHITA

Date: November 13, 2009